

# DCR5790M28

# **Phase Control Thyristor**

DS6121-1 August 2013 (LN30853)

## **FEATURES**

- **Double Side Cooling**
- **High Surge Capability**

**High Power Drives** 

Static Switches

**VOLTAGE RATINGS** 

Part and

Ordering

Number

DCR5790M28

DCR5790M26

DCR5790M24

DCR5790M22

High Voltage Power Supplies

**Repetitive Peak** 

Voltages

 $V_{\text{DRM}}$  and  $V_{\text{RRM}}$ v

2800

2600

2400

2200

Conditions

V<sub>DSM</sub> & V<sub>RSM</sub> =

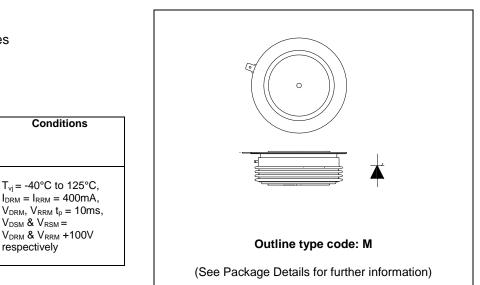
respectively

**APPLICATIONS** 

### **KEY PARAMETERS**

V <sub>DRM</sub>	2800 V
I <sub>T(AV)</sub>	5790 A
ITSM	75000 A
dV/dt*	1000 V/µs
dl/dt	250 A/µs

#### \* Higher dV/dt selections available



Lower voltage grades available.

### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

#### DCR5790M28

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.





### **CURRENT RATINGS**

T<sub>case</sub> = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	5790	А
I <sub>T(RMS)</sub>	RMS value	-	9090	А
Ι <sub>Τ</sub>	Continuous (direct) on-state current	-	8310	А

## SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}C$	75.0	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	V <sub>R</sub> = 0	28.10	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Condition	S	Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.005	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Double side cooled	DC	-	0.0015	°C/W
T <sub>vj</sub>	Virtual junction temperature	Blocking V <sub>DRM</sub> / V <sub>RRM</sub>		-40	125	°C
T <sub>stg</sub>	Storage temperature range			-40	140	°C
Fm	Clamping force			80	100	kN

# DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditio	ns	Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	400	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% $V_{DRM}$ , $T_j$ = 125°C, gate open		1000	-	V/µs
dl/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 4000A	Repetitive 50Hz	-	250	A/µs
		Gate source $30V$ , $10\Omega$ ,	Non-repetitive	-	1000	A/µs
		$t_r < 0.5 \mu s, T_j = 125^{\circ}C$				
VT	On-state voltage	I <sub>T</sub> = 3000A, T <sub>case</sub> = 125°C			1.14	V
V <sub>T(TO)</sub>	Threshold voltage – Low level	T <sub>case</sub> = 125°C		-	0.90	V
r <sub>T</sub>	On-state slope resistance – Low level	T <sub>case</sub> = 125°C		-	0.080	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% V_{DRM}$ , gate source	30V, 10Ω	-	3.0	μs
		$t_r=0.5\mu s, T_j=25^\circ C$				
tq	Turn-off time	$T_j = 125^{\circ}C, V_R = 100V, dl/dt$	= 1.5A/µs,	-	600	μs
		$dV_{DR}/dt = 20V/\mu s$ linear to 67	7% V <sub>DRM</sub>			
Qs	Stored charge	I <sub>T</sub> = 2000A, tp = 1000us,T <sub>j</sub> = 125°C, dl/dt =1.5A/μs,		-	4000	μC
I <sub>RR</sub>	Reverse recovery current			-	100	А
ار	Latching current	T <sub>j</sub> = 25°C,		-	1	А
I <sub>H</sub>	Holding current	T <sub>j</sub> = 25°C,		-	200	mA

# GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V <sub>GT</sub>	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	3	V
V <sub>GD</sub>	Gate non-trigger voltage	At 40% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	TBD	V
I <sub>GT</sub>	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	300	mA
I <sub>GD</sub>	Gate non-trigger current	At 40% V <sub>DRM,</sub> T <sub>case</sub> = 125°C	TBD	mA

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## CURVES

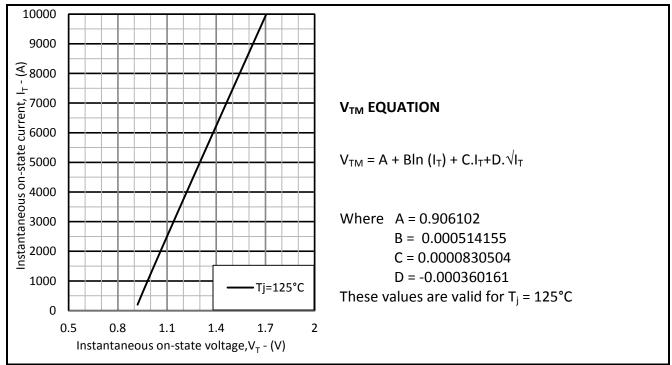


Fig.2 Maximum & minimum on-state characteristics

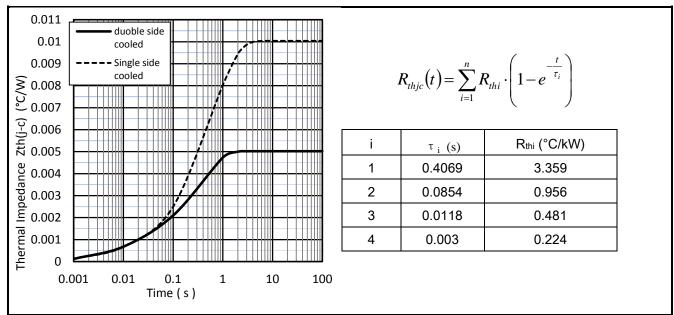
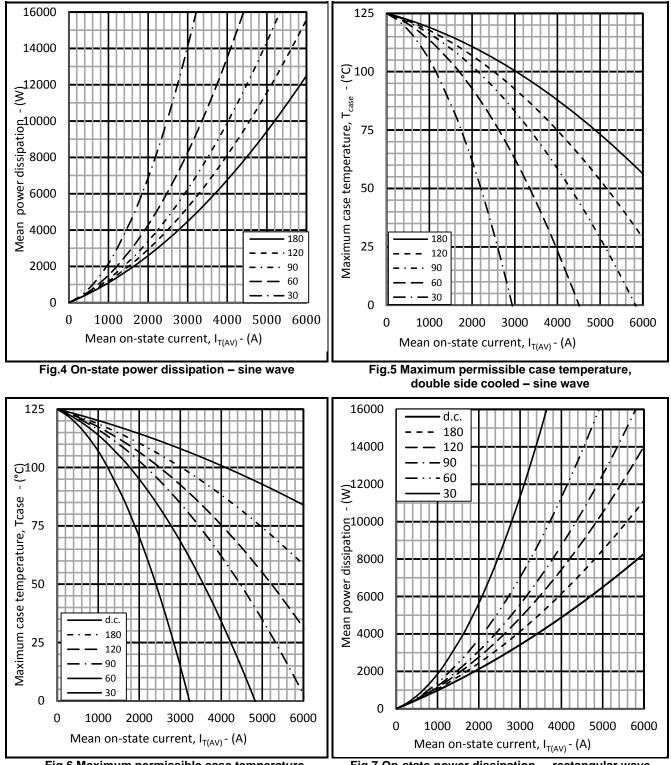
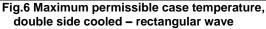


Fig.3 Maximum (limit) transient thermal impedance - junction to case (°C/W)

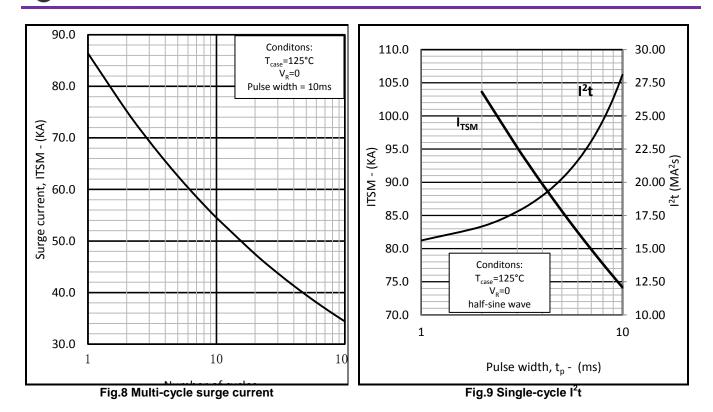












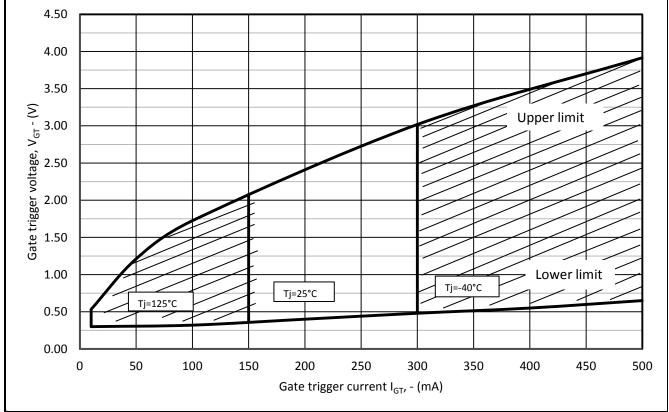


Fig.10 Gate characteristics

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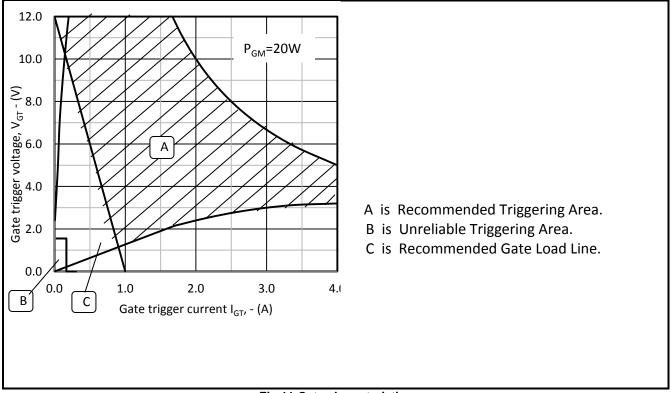


Fig.11 Gate characteristics



### PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

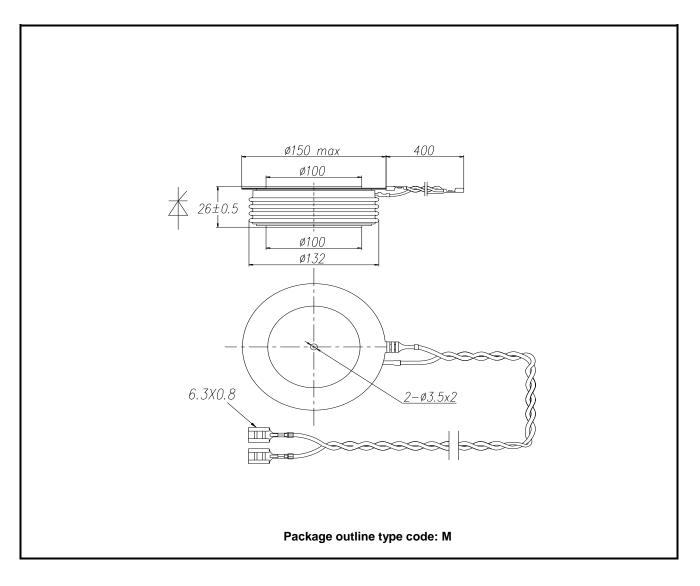


Fig.12 Package outline



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